PCN Number:	20211108000.1	**PCN Date:**	December 17, 2021
Title:	Qualification of a new mount compound for select devices		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
Proposed 1st Ship Date:	Mar. 17, 2022	**Estimated Sample Availability:**	Date provided at sample request

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Material
☒	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

PCN Details

Description of Change:

This PCN is to inform of a new mount compound qualification for the devices in the product affected section as follows:

What	Current	New
Mount Compound	SID#A-18	**SID#A-22**

Reason for Change:

Continuity of supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

None

Product Affected:

TPS62841DGRR	TPS62842DGRR

Approve Date 15-Apr-2020

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TPS62842DGR
AC	Autoclave 121C	96 hours	3/231/0
CDM	ESD - CDM	500V	1/3/0
HAST	Biased HAST, 130C/85%RH	96 hours	3/231/0
HBM	ESD - HBM	1000 V	1/3/0
HTOL	High Temperature operating life, 150C	300 hours	3/231/0
HTSL	High Temp Storage Life 170C	420 Hours	3/231/0
LU	Latch-up	100mA	1/3/0
TC	Temperature Cycle, -65/150C	500 cycles	3/231/0
Additional reliability testing on the leads:			
SD	Solderability test with 155C Dry Bake preconditioning	Pb Free solder	3/66/0
LP	Lead pull	-	3/18/0
LF	Lead Fatigue	-	3/66/0
LFA	Lead finish adhesion	-	3/45/0

- Qual Device TPS62842DGR is qualified at LEVEL1-260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
Green/Pb-free Status:
Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

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